



Amendments to the Claims

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An anisotropically conductive adhesive, comprising:  
crushable microcapsules, that each enclose a first substance and a conductive particle;  
a second substance that is curable by a reaction with the first substance, the  
microcapsules and a third substance being dispersed in the second substance prior to curing,  
the third substance curable by a reaction with the second substance, the reaction occurring by  
heating to form the adhesive.

2. (Currently Amended) An anisotropically conductive adhesive, comprising:  
conductive particles; each having a plurality of crushable microcapsules that  
adhere to the conductive particles, that wherein each microcapsule ~~enclose~~ encloses a first  
substance ~~that adheres to each of the conductive particles; and~~  
a second substance that is curable by a reaction with the first substance, the  
conductive particles and the microcapsules being dispersed in the second substance; and  
a third substance being dispersed in the second substance prior to curing, the  
third substance being curable by a reaction with the second substance during heating to form  
the adhesive.

3. (Original) The anisotropically conductive adhesive according to Claim 1,  
the first substance being any substance or mixture of amines, imidazoles, acid  
anhydrides, and phenols; and  
the second substance being an uncured epoxy resin.

4. (Original) The anisotropically conductive adhesive according to Claim 1,  
the first substance being an uncured epoxy resin; and

the second substance being any substance or mixture of amines, imidazoles, acid anhydrides, and phenols.

5. (Original) The anisotropically conductive adhesive according to Claim 1, capsule walls of the microcapsules comprising a thermoplastic resin.

6. (Canceled)

7. (Withdrawn) A mounting method, comprising:  
applying the anisotropically conductive adhesive according to Claim 1 onto either mounting surface of a pair of mounting components; and  
pressing the pair of mounting components to crush the microcapsules between mounting conductors provided on the pair of mounting components, the mounting conductors holding the conductive particles and being bonded with each other.

8. (Withdrawn) A mounting method, comprising:  
applying the anisotropically conductive adhesive according to Claim 4 onto either mounting surface of a pair of mounting components;  
pressing the pair of mounting components to crush the microcapsules between mounting conductors provided on the pair of mounting components, the mounting conductors holding the conductive particles and being bonded with each other; and  
curing the anisotropically conductive adhesive by heating to bond the pair of mounting components with each other.

9. (Withdrawn) An electro-optical device module manufactured by the mounting method according to Claim 7,  
one of the pair of mounting components being a substrate having display elements and constituting a part of an electro-optical device; and  
the other of the pair of mounting components being a substrate on which a drive device for the display elements is mounted.

10. (Withdrawn) An electronic device manufactured by the mounting method according to Claim 7.
11. (Original) The anisotropically conductive adhesive according to Claim 2,  
the first substance being any substance or mixture of amines, imidazoles, acid anhydrides, and phenols; and  
the second substance being an uncured epoxy resin.
12. (Original) The anisotropically conductive adhesive according to Claim 2,  
the first substance being an uncured epoxy resin; and  
the second substance being any substance or mixture of amines, imidazoles, acid anhydrides, and phenols.
13. (Original) The anisotropically conductive adhesive according to Claim 2, capsule walls of the microcapsules comprising a thermoplastic resin.
14. (Canceled)
15. (Withdrawn) A mounting method, comprising:  
applying the anisotropically conductive adhesive according to Claim 2 onto either mounting surface of a pair of mounting components; and  
pressing the pair of mounting components to crush the microcapsules between mounting conductors provided on the pair of mounting components, the mounting conductors holding the conductive particles and being bonded with each other.
16. (Withdrawn) An electro-optical device module manufactured by the mounting method according to Claim 8,  
one of the pair of mounting components being a substrate having display elements and constituting a part of an electro-optical device; and  
the other of the pair of mounting components being a substrate on which a drive device for the display elements is mounted.

17. (Withdrawn) An electronic device manufactured by the mounting method according to Claim 8.

18. (New) The anisotropically conductive adhesive according to Claim 1, the third substance being any substance or mixture of imidazoles, acid anhydrides, and phenols.

19. (New) The anisotropically conductive adhesive according to Claim 2, the third substance being any substance or mixture of imidazoles, acid anhydrides, and phenols.